



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20180110007
Datasheet for INA138, INA168
Information Only**

Date: January 19, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services


Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA138NA/250	null
INA168NA/250	null
INA168NA/3K	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180110007	PCN Date:	January 19, 2018
Title:	Datasheet for INA138, INA168		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
Notification Details			
Description of Change:			
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>			
		INA138, INA168 <small>SBOS122E – DECEMBER 1999 – REVISED DECEMBER 2017</small>	
Changes from Revision D (December 2014) to Revision E			Page
• Added reference design link to navigation bar at the top of the front page			1
• Changed body size from 18.00 mm × 18.00 mm to 2.90 mm × 1.60 mm in Device Information table.....			1
• Changed pin numbers in pin functions table to match pin configuration figure.....			3
• Changed <i>Absolute Maximum Ratings</i> table for clarity; no values were changed			4
• Changed <i>Recommended Operating Conditions</i> table; moved some content from <i>Electrical Characteristics</i> table, but no values changed			4
• Changed all values in Thermal Information table			5
• Changed <i>Electrical Characteristics</i> table; reformatted for clarity; moved some content to <i>Recommended Operating Conditions</i> table, and deleted duplicate content.....			5
• Changed common-mode rejection test conditions to better highlight each device in <i>Electrical Characteristics</i> table			5
• Changed offset voltage vs temperature to offset voltage drift in <i>Electrical Characteristics</i> table.....			5
• Changed offset voltage vs power supply test conditions to better highlight each device in <i>Electrical Characteristics</i> table ..			5
• Changed reference in text from Figure 10 to Figure 11 in last paragraph of <i>Selecting the Shunt Resistor and R_L</i> section			12
The datasheet number will be changing.			
Device Family	Change From:	Change To:	
INA138, INA168	SBOS122D	SBOS122E	
These changes may be reviewed at the datasheet links provided.			
http://www.ti.com/product/INA138			
Reason for Change:			
To accurately reflect device usage in specific application use cases.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
INA138NA/250	INA138NA/3KG4	INA168NA/250	INA168NA/3K

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com